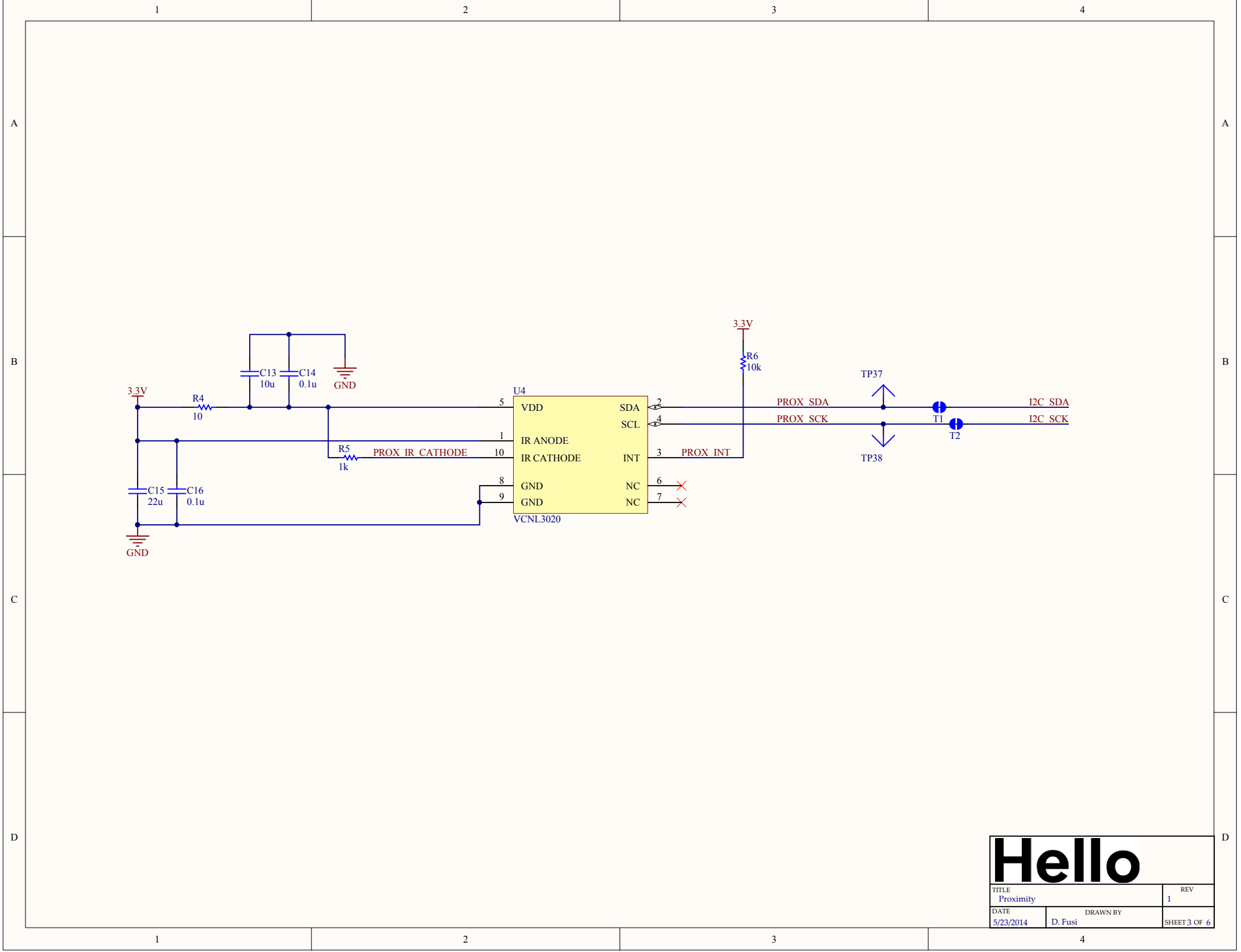


Hello

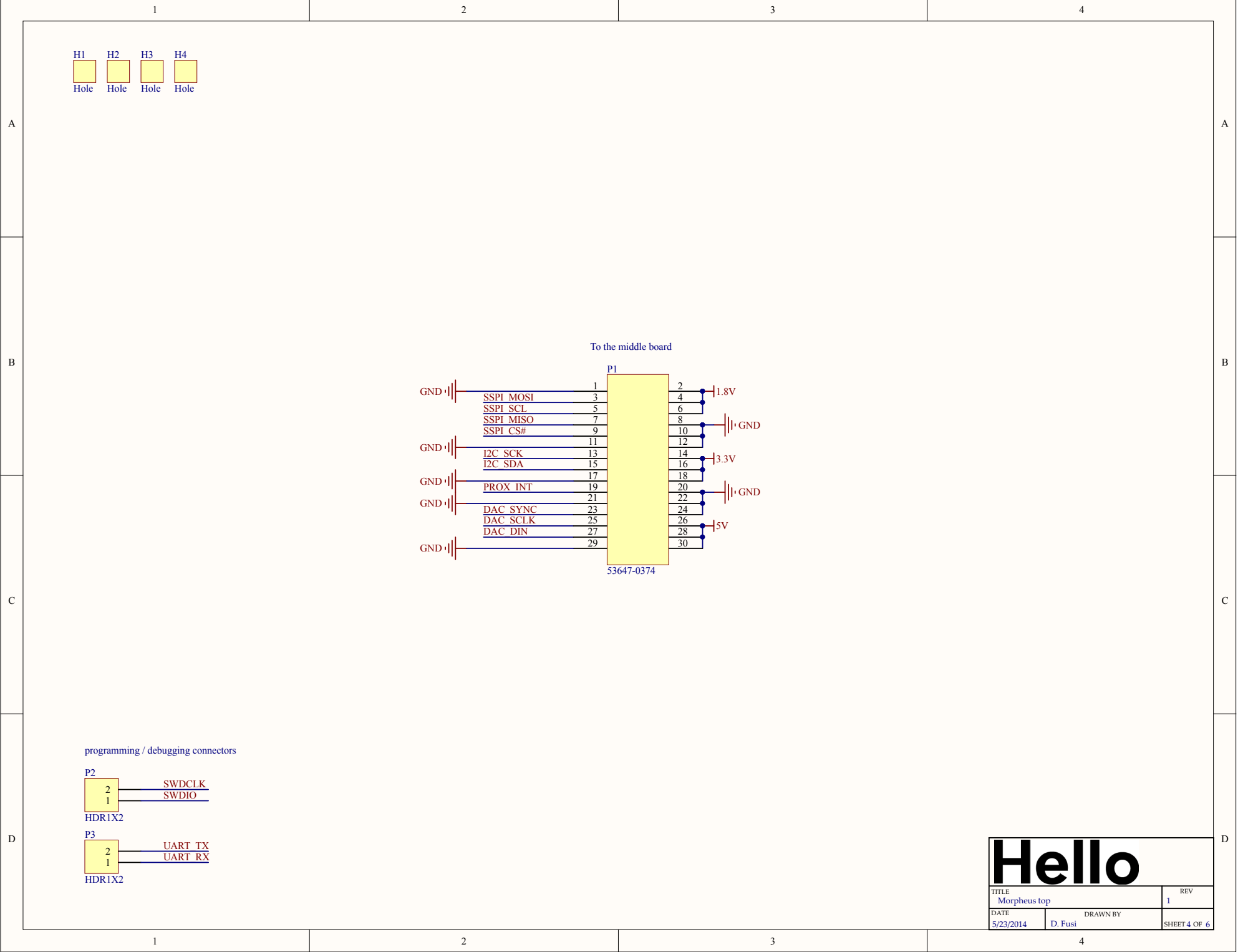
TITLE		REV
ALS		1
DATE	DRAWN BY	SHEET 1 OF 6
5/23/2014	D. Fusi	





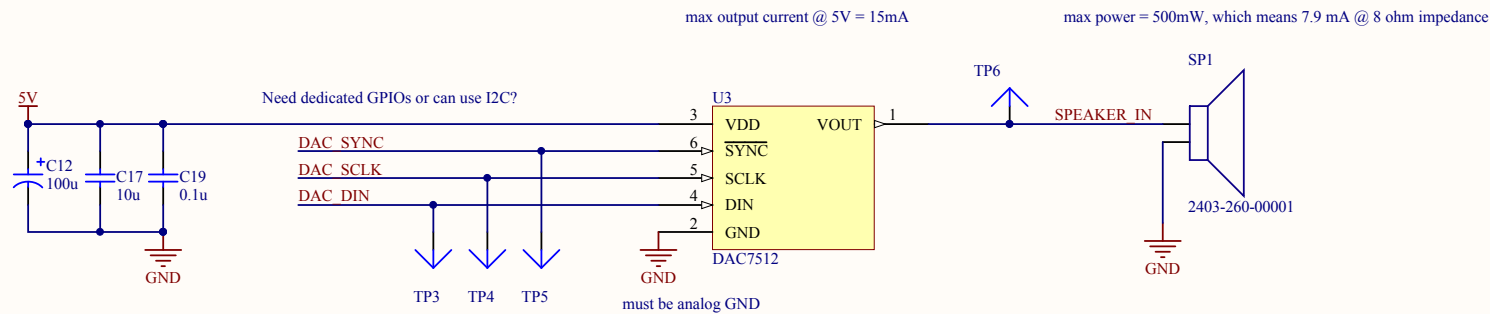
Hello

TITLE Proximity		REV 1
DATE 5/23/2014	DRAWN BY D. Fusi	SHEET 3 OF 6

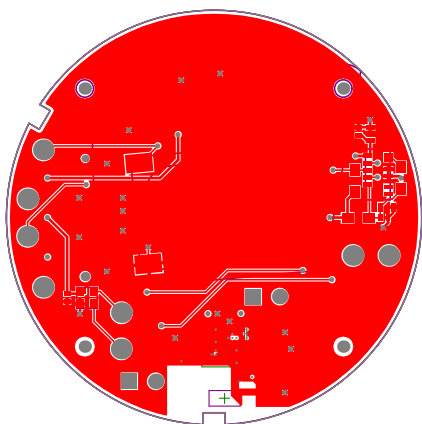


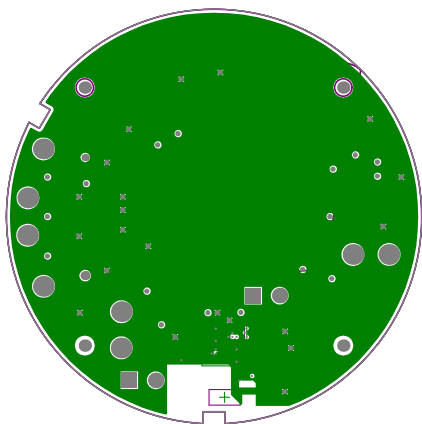
Hello

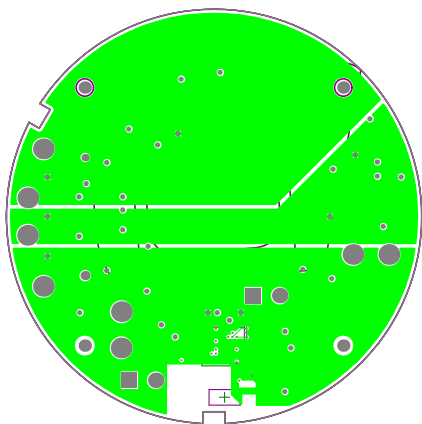
TITLE		REV
Morpheus top		1
DATE	DRAWN BY	SHEET 4 OF 6
5/23/2014	D. Fusi	



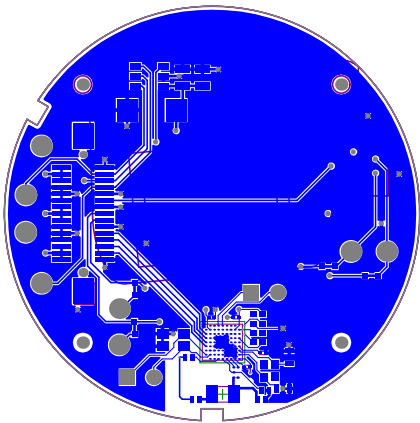
Hello		
TITLE	Speaker	REV
DATE	DRAWN BY	1
5/21/2014	D. Fusi	SHEET 5 OF 6

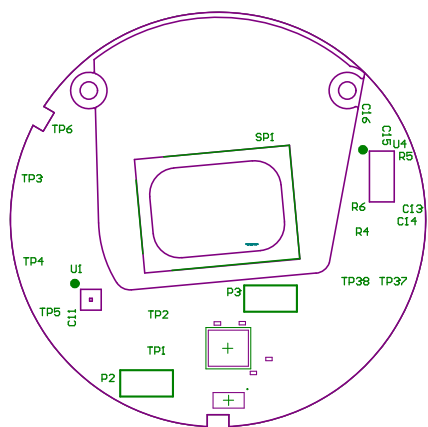


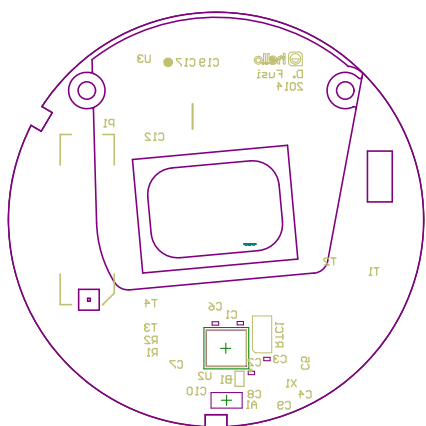


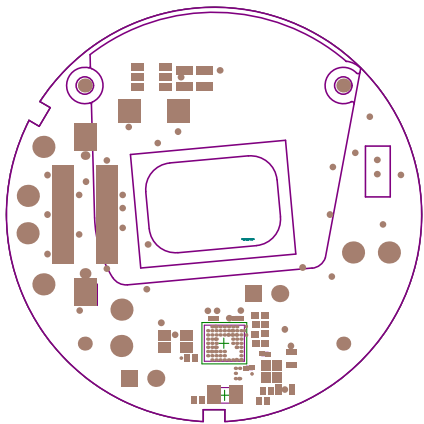


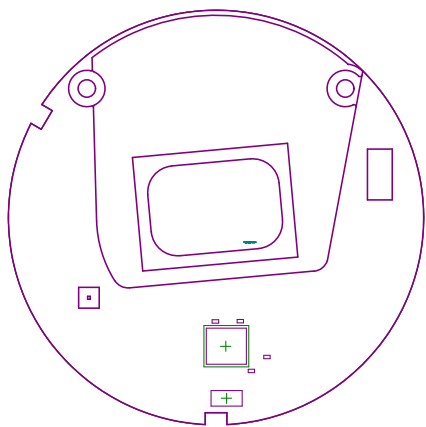


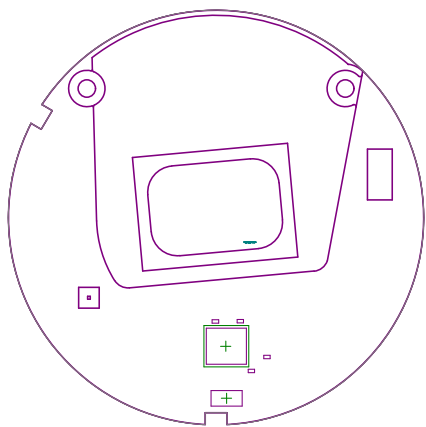


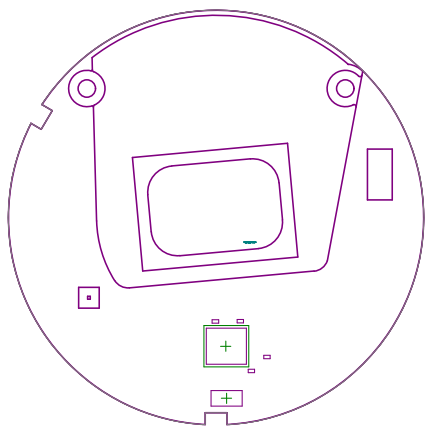


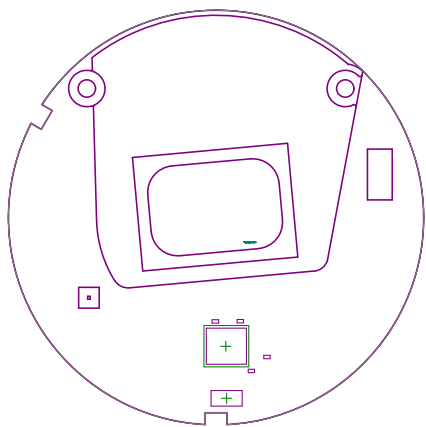




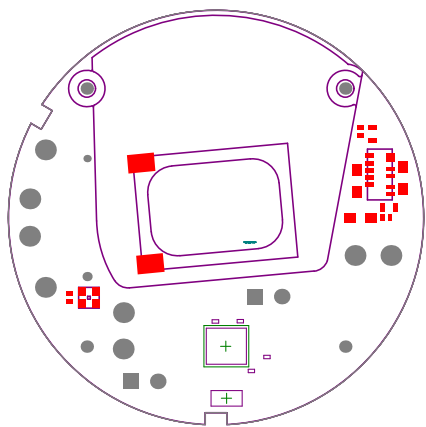


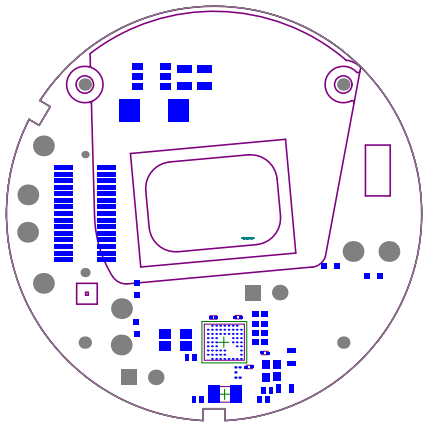


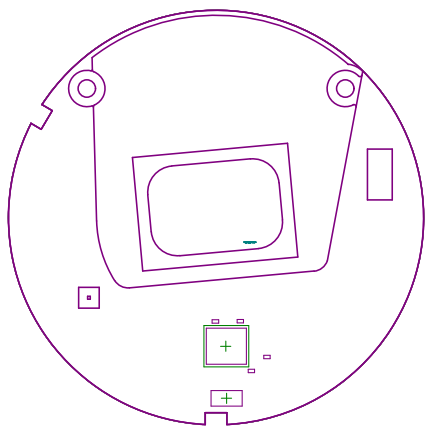












# Fabrication / Assembly Notes

1. Material: Rigid
2. Number of electrical layers: 6
3. Trace / Space minimum: 5mil (all layers)
4. Thickness: 1.25mm (finished)
5. Finish: ENIG plating on exposed copper
6. Soldermask: per IPC-SM-840, color green registration within +/- 50um of circuit layer
7. Silkscreen: do print silkscreen on top and bottom layers
8. RoHS: parts shall be RoHS compliant as per European Union directive 2002/95/EC
9. Board must be lead free process compatible and able to withstand minimum of 5 cycles at 250 degrees celsius
10. All Test/QA/QC markings to be made on back side of PCB

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Paste				
2	Top Overlay				
3	Top Solder	Solder Resist	0.010mm	3.5	
4	Top Layer	Copper	0.036mm		
5	Dielectric 1	FR-4	0.320mm	4.8	
6	Bottom Layer	Copper	0.036mm		
7	Bottom Solder	Solder Resist	0.010mm	3.5	
8	Bottom Overlay				
9	Bottom Paste				

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type	Physical Length	Rout Path Length
⊠	1	0.700mm (27.56mil)	NPTH	Round		
⊛	1	0.900mm (35.43mil)	NPTH	Round		
□	4	0.900mm (35.43mil)	PTH	Round		
▽	12	1.700mm (66.93mil)	PTH	Round		
⊗	17	0.100mm (3.94mil)	PTH	Round		
○	38	0.200mm (7.87mil)	PTH	Round		
	73 Total					

